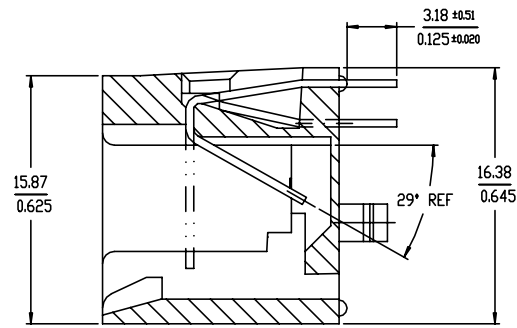
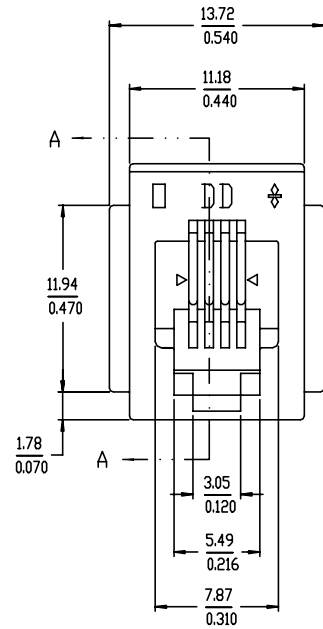
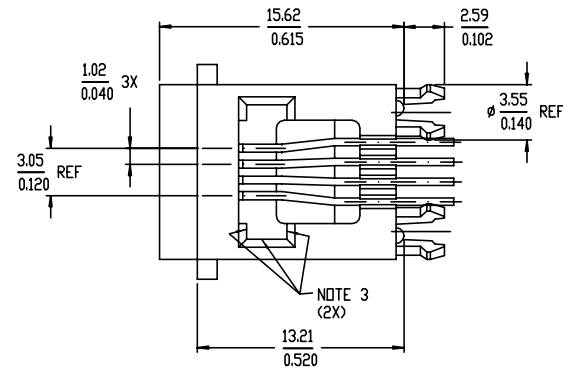
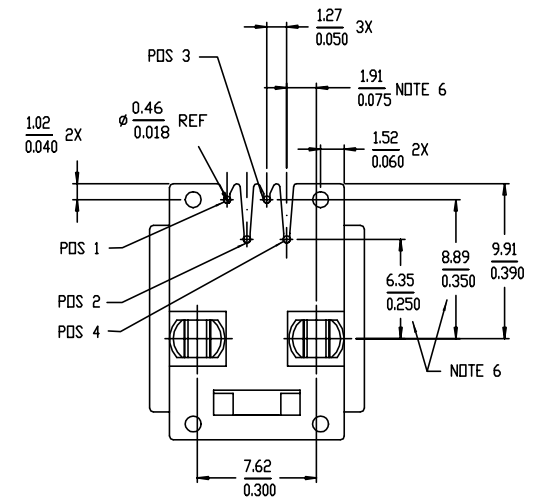


PRODUCT NO.
SEE CHART



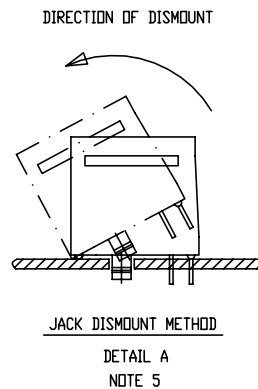
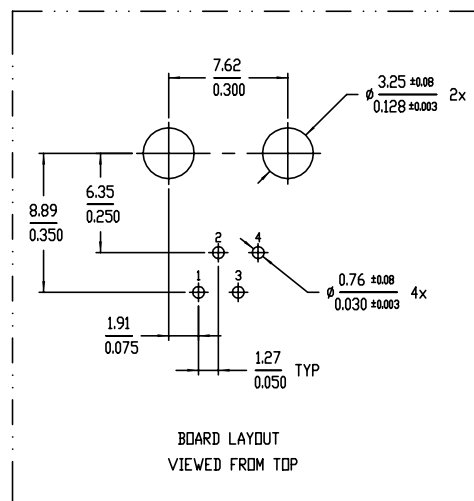
SECTION A-A



mat'l. code				surface ISO1302 ✓		tolerance ISO1101 ISO406		projection 		product family MOD JACK									
ltr ecn nodr				date		tolerances unless otherwise specified		title		4 POS VERT. SNAP PEG PCB III MOD JACK ASSY									
K		S00022		LOW		01/25/00		angle mm											
L		N04-0102		YS		11/23/04		0.X±0.3											
M		N08-0097		SH MMD		09/25/08		0.XX±0.15											
								0.XXX±0.05											
N		N08-0170		SH MMD		10/09/08		dr		M CHENG		7/13/01		dwg no		sheet 1 of 2		size A4	
P		ELX-N-010673		SH MMD		3/14/12		engr		M CHENG		7/13/01							
								chr		M CHENG		7/13/01							
								appd		J HSIA		7/20/01		type		Product Customer Drawing			
sheet index		revision		P		P													
		sheet		1		2													

PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	NOTES
90511-001 -001LF -001HLF	ALL	5u" Au + high performance lubricant	BLACK
-002 -002LF -002HLF	ALL	5u" Au + high performance lubricant	BLACK
-003 -003LF	ALL	5u" Au + high performance lubricant	GREY
-004 -004LF	ALL	5u" Au + high performance lubricant	GREY
-005 -005LF -005HLF	ALL	50u" / 1.27u GXT	BLACK

LEAD FREE PRODUCT NO.
MEETS PIP PROCESS PRODUCT NO.



PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	REMARKS
90511-101 -101LF -101HLF	ALL	5u" Au + high performance lubricant	NOT TOOLED
-102 -102LF -102HLF	ALL	5u" Au + high performance lubricant	NOT TOOLED

NOTES :

- P/NO WITH DASH 0XX -NORMAL WAVE SOLDERING APPLICATION.
P/NO WITH DASH 1XX -IR REFLOW APPLICATION (NOT TOOLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57//,062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTDEMR .

mat'l. code	surface	tolerance	projection	product family
ISO1302	ISO1101	ISO406	mm	MOD JACK
tolerances unless otherwise specified	0.X±0.3	0.XX±0.15	scale 2.0	4 POS VERT. SNAP PEG
angle	0°±2'	0.XXX±0.05		PCB III MOD JACK ASSY
l t r e c n n o d r	date			
K S00022 LOW 01/25/00				
L N04-0102 YS 11/23/04				
M N08-0097 SH MMD 09/25/08				
N N08-0170 SH MMD 10/09/08	dr	M CHENG	7/13/01	
P ELX-N-010673 SH MMD 3/14/12	enr	M CHENG	7/13/01	
	chr	M CHENG	7/13/01	
	appd	J HSIA	7/20/01	
sheet	revision			
index	sheet			